



**Surface Mount Superfast Recovery Rectifier**

**Reverse Voltage – 50 to 600 V**

**Forward Current – 3 A**

**FEATURES**

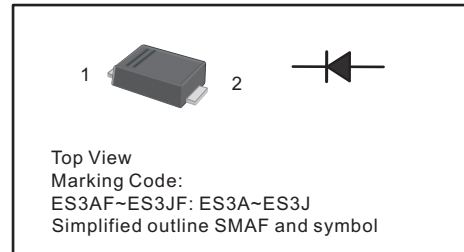
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

**MECHANICAL DATA**

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg / 0.00095oz

**PINNING**

PIN	DESCRIPTION
1	Cathode
2	Anode



**Absolute Maximum Ratings and Characteristics**

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

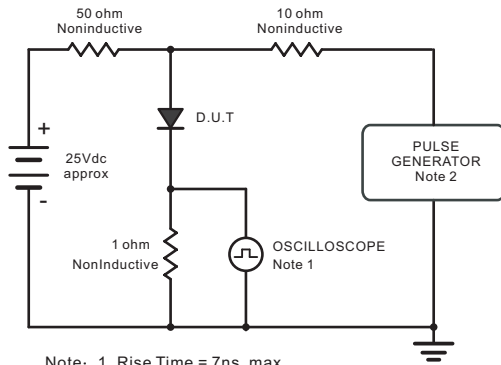
Parameter	Symbols	ES3AF	ES3BF	ES3CF	ES3DF	ES3EF	ES3GF	ES3JF	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	150	200	300	400	600	V
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at $T_c = 125\text{ °C}$	$I_{F(AV)}$	3							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	$I_{FSM}$	80							A
Maximum Forward Voltage at 3 A	$V_F$	1				1.25		1.68	V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25\text{ °C}$ $T_a = 125\text{ °C}$	$I_R$	5 100							$\mu A$
Typical Junction Capacitance at $V_R = 4V, f = 1MHz$	$C_j$	40							pF
Maximum Reverse Recovery Time <sup>(1)</sup>	$t_{rr}$	35							ns
Typical Thermal Resistance <sup>(2)</sup>	$R_{\theta JA}$ $R_{\theta JC}$	50 16							$^{\circ}C/W$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150							$^{\circ}C$

(1) Measured with  $I_F = 0.5\text{ A}, I_R = 1\text{ A}, I_{rr} = 0.25\text{ A}$ .

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.



Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.  
Input Impedance = 1megohm, 22pF.  
2. Rises Time = 10ns, max.  
Source Impedance = 50 ohms.

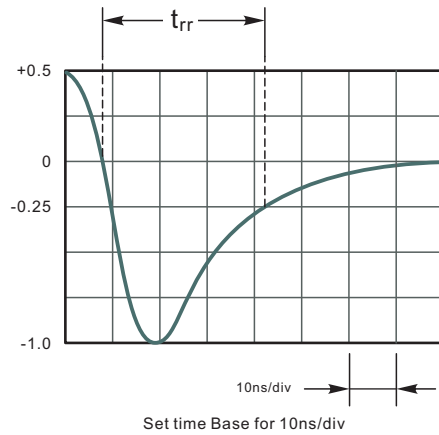


Fig.2 Maximum Average Forward Current Rating

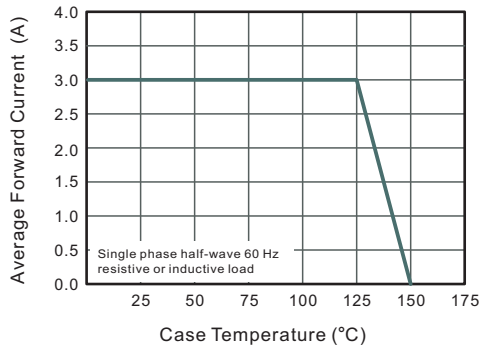


Fig.3 Typical Reverse Characteristics

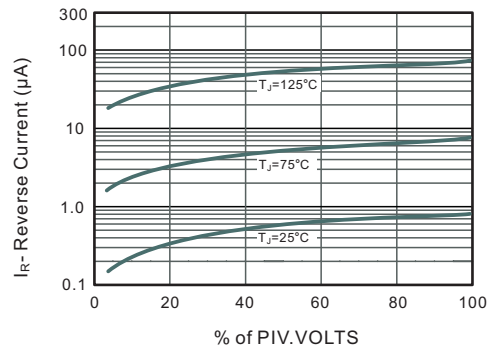


Fig.4 Typical Forward Characteristics

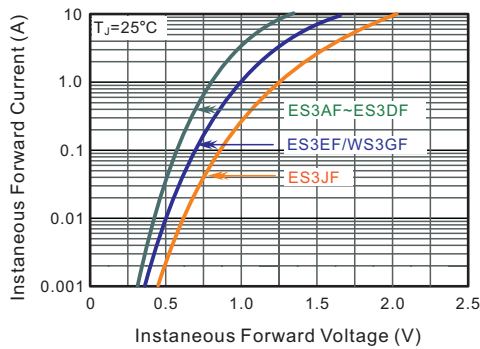


Fig.5 Typical Junction Capacitance

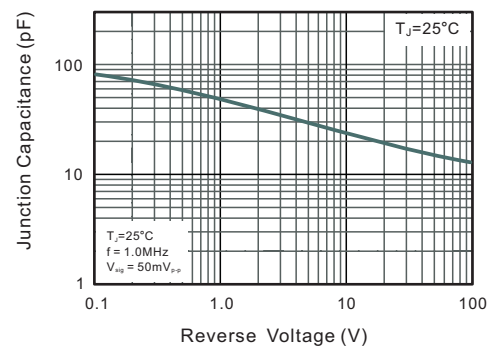
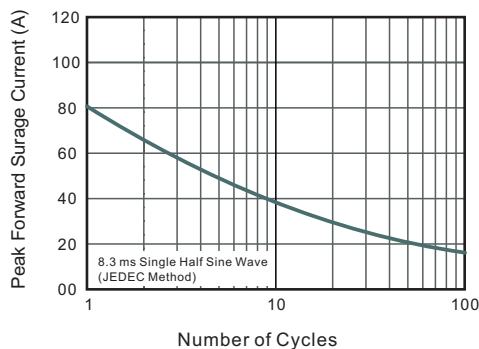


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current

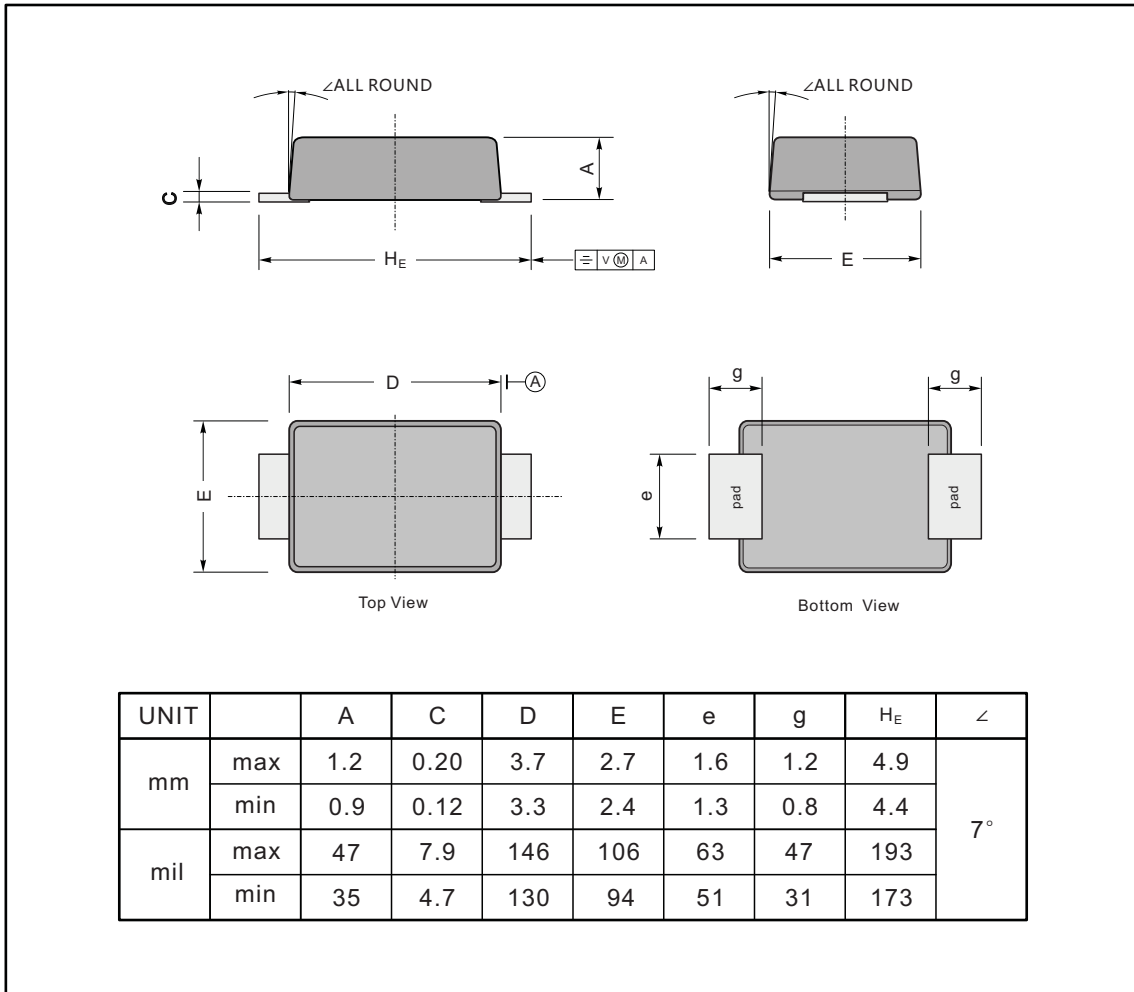




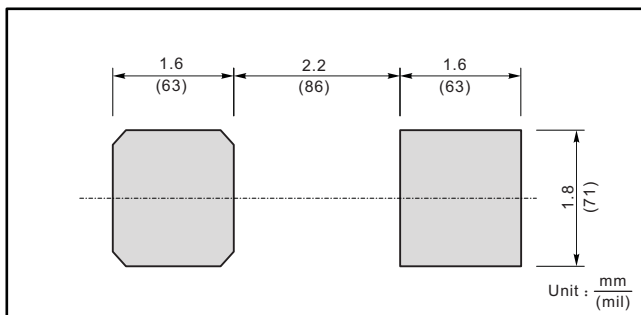
**PACKAGE OUTLINE**

Plastic surface mounted package; 2 leads

SMAF



**The recommended mounting pad size**



**Marking**

Type number	Marking code
ES3AF	ES3A
ES3BF	ES3B
ES3CF	ES3C
ES3DF	ES3D
ES3EF	ES3E
ES3GF	ES3G
ES3JF	ES3J

单击下面可查看定价，库存，交付和生命周期等信息

[>>JINGDAO\(晶导\)](#)